

Amendment to the Claims:

This listing of the claims will replace all prior versions and listings of the claims in the application:

Claims 1-20 (Canceled).

21. (Currently amended) An apparatus for pretreating a semiconductor wafer prior to electroplating comprising:

a wafer jig constructed and arranged to carry ~~[[a]]~~ the semiconductor wafer therein, and wherein the wafer jig includes an opening therein for exposing a top surface of the semiconductor wafer;

a wetting solution supply tank connected to a pump, and the pump connected to a spray module for pumping wetting solution through a spray module and onto a semiconductor wafer carried in the wafer jig, and wherein the spray module includes a plurality of spray nozzles each constructed and arranged to spray wetting solution particles having a diameter less than 100 micrometers.

22. (Original) An apparatus as set forth in claim 21 wherein the spray module and the wafer jig are constructed and arranged to be movable with respect to each other.

23. (Original) An apparatus as set forth in claim 21 further comprising wafer jig holding machine constructed and arranged for oscillating reciprocally the wafer jig in at least a vertical direction with respect to the spray module.

24. (Currently amended) An apparatus as set forth in claim 21 ~~wherein the spray module includes a plurality of spray nozzles each constructed and arranged to spray wetting solution particles having a diameter less than 100 micrometers~~ further comprising an actuated robot connected to the wafer jig for moving the wafer jig in a vertical direction with respect to the nozzles.

25. (Original) An apparatus as set forth in claim 21 wherein the spray module includes a plurality of spray nozzles each constructed and arranged to spray wetting solution particles having a diameter ranging from 10-100 micrometers.

26. (Currently amended) An apparatus as set forth in claim 21 wherein the spray module includes three spray ~~nozzle~~ nozzles arranged in a triangular shape.